

# Contents

<b>Abstract</b>	<b>vii</b>
<b>Zusammenfassung</b>	<b>ix</b>
<b>Acknowledgements</b>	<b>xi</b>
<b>1 Introduction</b>	<b>1</b>
1.1 Single-walled nanotubes for chemical sensing . . . . .	2
1.2 Challenges in SWNT-based gas sensing . . . . .	3
1.3 Goals of this thesis . . . . .	3
1.4 Organization of the thesis . . . . .	4
<b>2 Theory and State-of-the-art</b>	<b>5</b>
2.1 SWNT field-effect transistors . . . . .	5
2.1.1 Structural and electronic properties . . . . .	6
2.1.2 The nanotube-metal contact . . . . .	6
2.1.3 Transport through the SWNT channel . . . . .	9
2.1.4 CNFET characteristics . . . . .	11
2.1.5 Non-idealities in CNFETs . . . . .	11
2.2 Carbon nanotube gas sensors . . . . .	16
2.2.1 Sensing mechanisms in carbon nanotube gas sensors . . . . .	16
2.2.2 Sensor kinetics . . . . .	21
2.2.3 Response and recovery time . . . . .	24
2.2.4 Tuning selectivity . . . . .	25
2.2.5 Sensor recovery methods . . . . .	26
2.2.6 Self-heating for sensor recovery . . . . .	28
2.2.7 Other low-power sensor technologies . . . . .	29
2.3 Review of research objectives . . . . .	33
<b>3 Wafer scale integration of nanotube transistors</b>	<b>35</b>
3.1 Approaches to SWNT integration . . . . .	35
3.1.1 Available approaches . . . . .	35
3.2 The wafer-scale integration process . . . . .	36
3.2.1 Process optimization . . . . .	39
3.3 Statistical Process Control . . . . .	44
3.3.1 Process Control Monitor: Concept . . . . .	45
3.4 Length and density monitors . . . . .	46
3.4.1 Experimental validation . . . . .	53
3.4.2 Perturbation detection . . . . .	56

## Contents

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3.4.3	PCM Resolution	56
3.4.4	Valid estimation range	57
3.5	Device monitors	58
3.5.1	Device monitor design	59
3.5.2	Device monitor Optimization	60
3.5.3	Experimental results	62
3.5.4	Chip-to-chip variation	66
3.5.5	Run reproducibility	66
3.5.6	Detecting process variation	67
3.6	Implementation on 100 mm wafers	67
3.6.1	Modifications to the fabrication process	68
3.6.2	Electrical Measurements	70
3.6.3	Results and discussion: length and density monitors	70
3.6.4	Results and discussion: Device monitors	72
3.7	Chapter summary	80
<b>4</b>	<b>Ultra-low power gas sensing with carbon nanotubes</b>	<b>81</b>
4.1	CNFET arrays as gas sensors	81
4.1.1	Sample Fabrication	81
4.1.2	Measurement Setup	82
4.1.3	Sensor response	83
4.1.4	Concentration dependence	85
4.1.5	Baseline drift	86
4.1.6	Noise characterization	88
4.1.7	Sensor recovery	90
4.1.8	Self-heating in substrate-bound devices	92
4.1.9	Summary	95
4.2	Suspended, ultraclean NO <sub>2</sub> sensors	95
4.2.1	Sample Fabrication	96
4.2.2	Characterization: Unpassivated sensors	98
4.2.3	Characterization: Passivated sensors	107
4.3	Self-heated recovery of suspended gas sensors	112
4.4	Designing the sensor architecture	118
4.4.1	Signal-to-noise ratio	119
4.4.2	Sensing mechanism	119
4.4.3	Self-heated recovery	121
4.5	Summary	122
<b>5</b>	<b>Conclusions and Outlook</b>	<b>123</b>
5.1	Wafer-scale integration	123
5.2	Carbon nanotube gas sensors	123
5.3	Future work	124
5.3.1	Short and medium-term research questions:	124
5.3.2	Long-term research questions:	126
5.4	Final remarks	126

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<b>Appendices</b>	<b>127</b>
<b>Appendix A Process Runsheets</b>	<b>129</b>
A.1 Process runsheet for chip-scale CNFET fabrication (run KC09) . . . . .	129
A.2 Process runsheet for wafer-scale CNFET fabrication (from run KC-F4) . . . .	130
<b>Appendix B Measurement setups</b>	<b>133</b>
B.1 Electrical measurements . . . . .	133
B.1.1 Pulsed gate sweep setup . . . . .	133
B.1.2 Constant-bias measurement setup . . . . .	133
B.1.3 Wafer-scale electrical measurement setup . . . . .	133
B.2 Gas flow system . . . . .	134
B.2.1 Setup at Siemens Corporate Technology, Munich . . . . .	134
B.2.2 Setup at Micro and Nanosystems ETH Zurich . . . . .	134
B.3 Gas chamber and miniature heater setup design . . . . .	134
B.3.1 Gas chamber design . . . . .	134
B.3.2 Miniature heater integration . . . . .	135
<b>Appendix C Optimality of the monitor designs</b>	<b>137</b>
<b>Appendix D Gas response of Contact-open, substrate-bound devices</b>	<b>141</b>
<b>Appendix E List of Fabrication runs and samples</b>	<b>145</b>
E.1 CNFET arrays on chips . . . . .	145
E.2 CNFET wafers . . . . .	146
E.3 Suspended transfer-devices . . . . .	147
E.4 Device geometries . . . . .	147
<b>Bibliography</b>	<b>149</b>
<b>Publications</b>	<b>169</b>